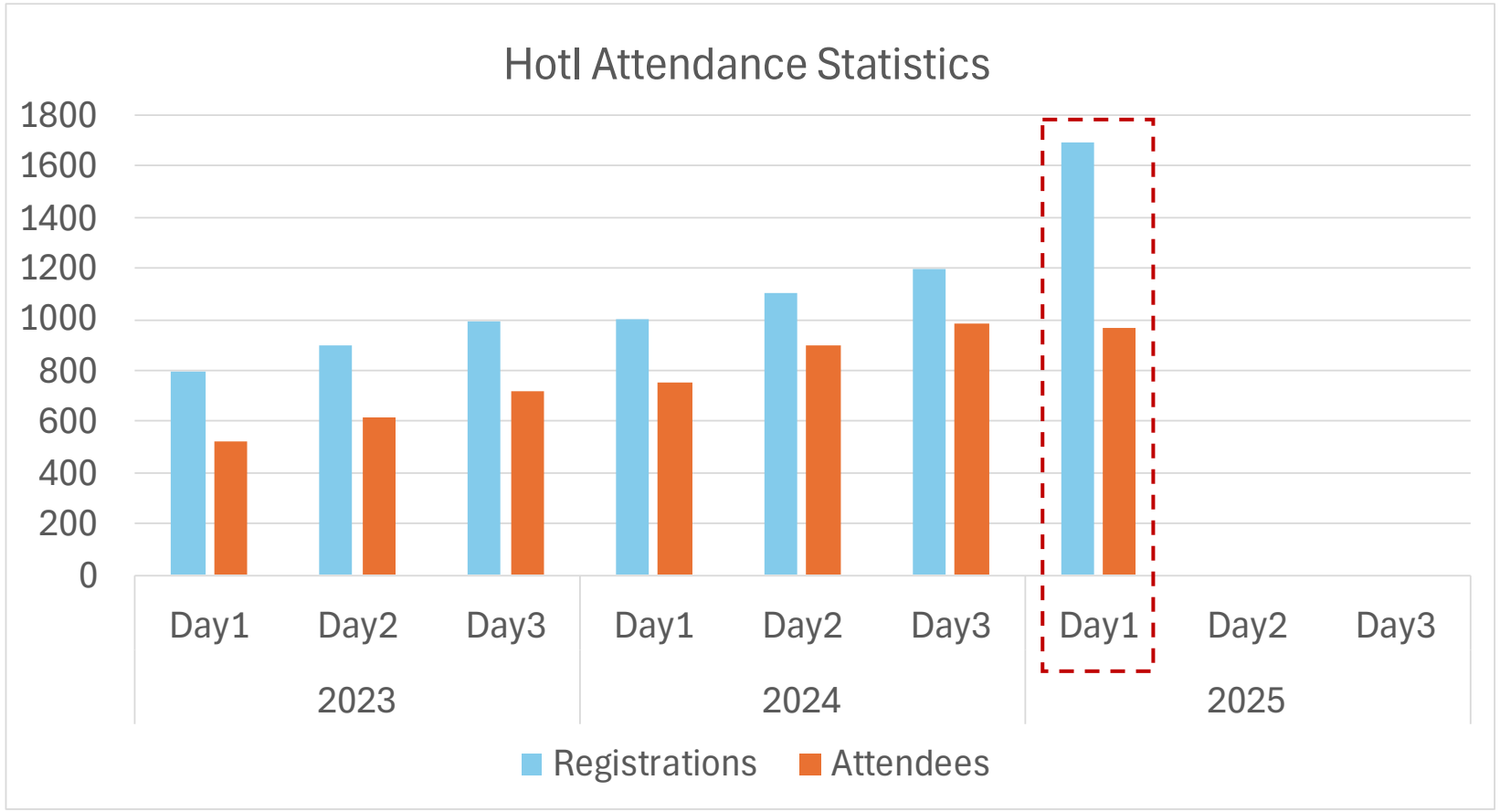
IEEE HotI 32 (2025)
Day2

Artem Y. Polyakov
General Chair

HOTI 2025
IEEE Symposium on High-Performance Interconnects
20-22 August 2025 • Virtual, United States

Day 1 Attendance Stats



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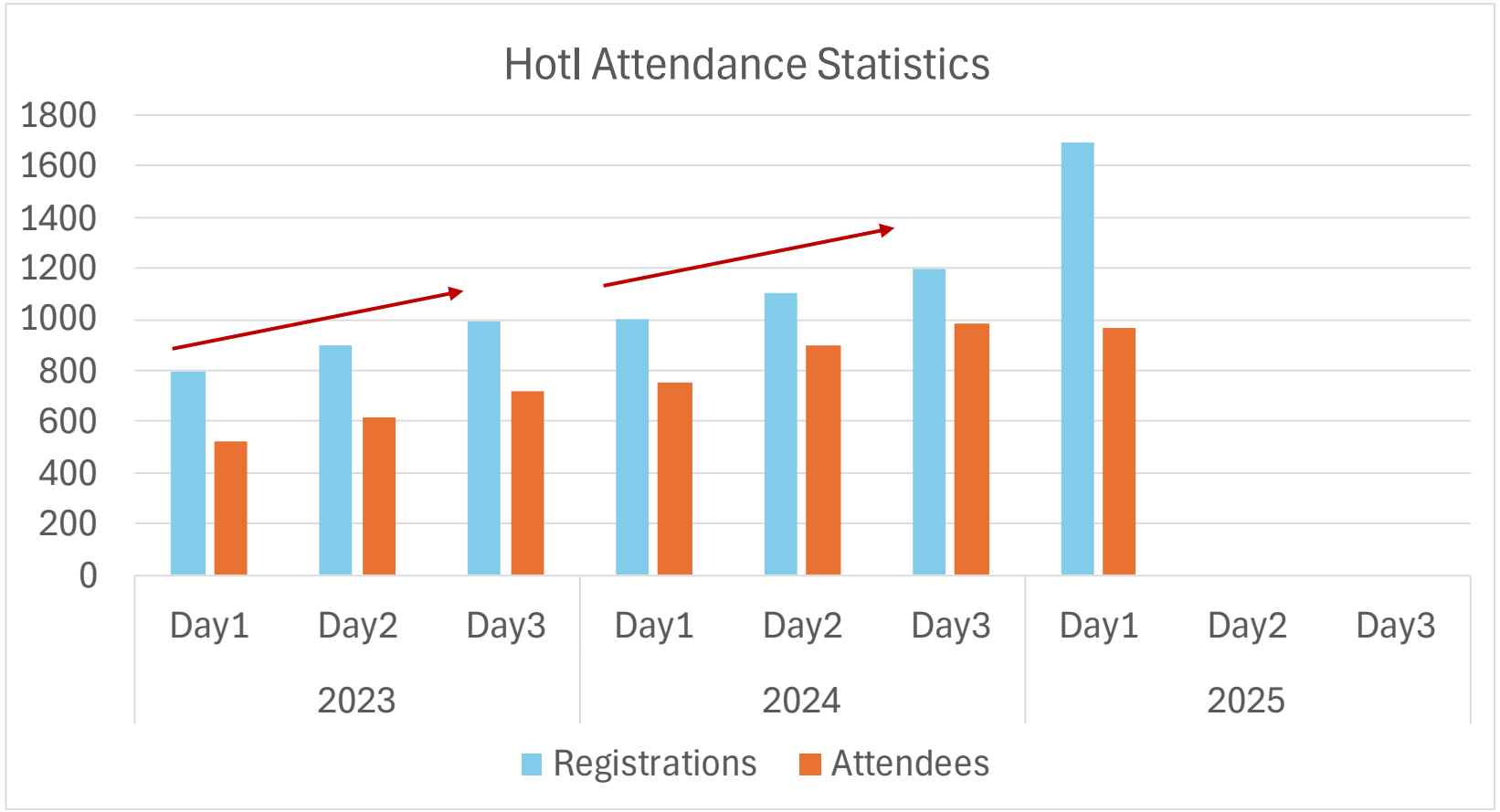

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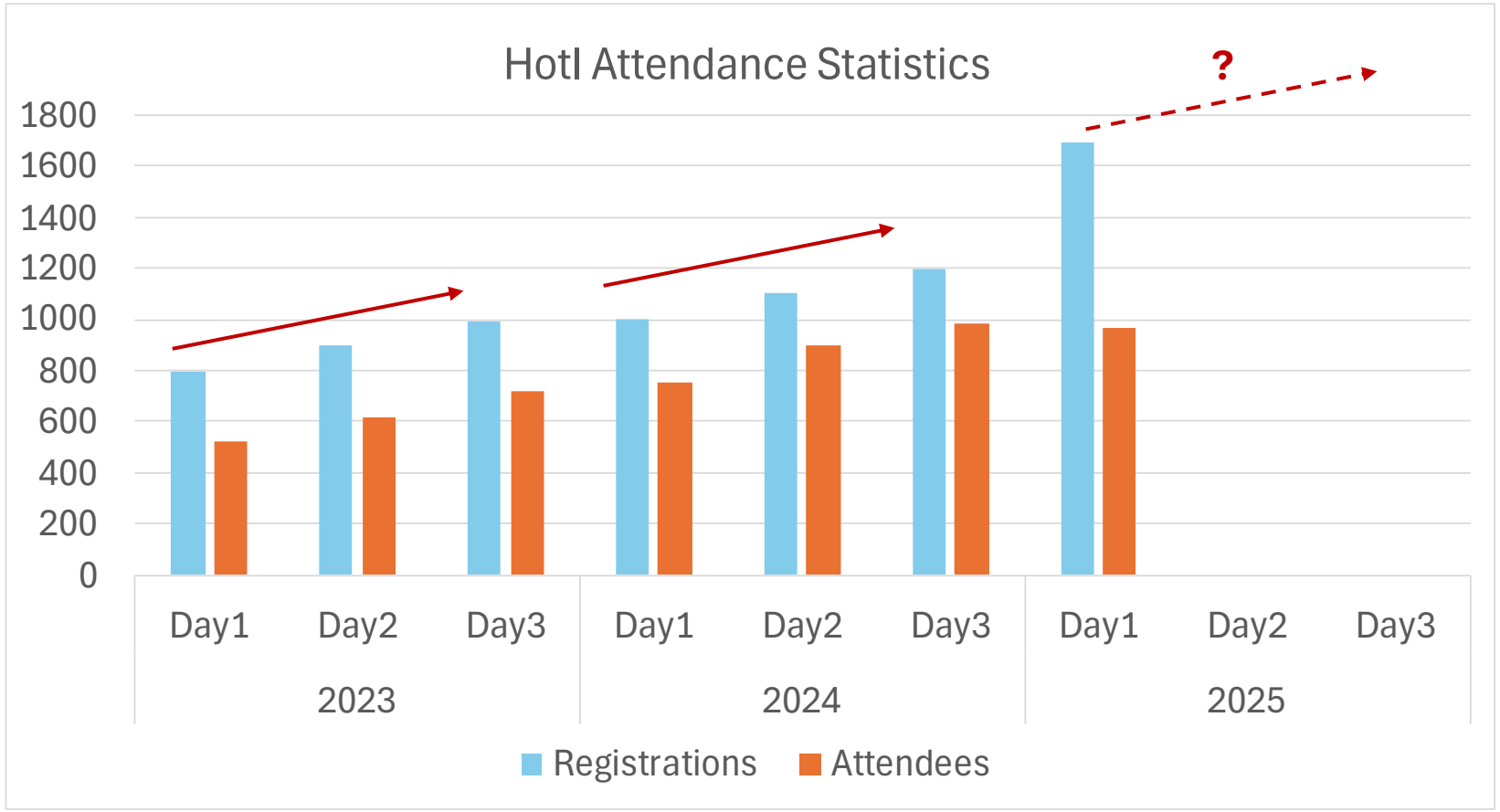

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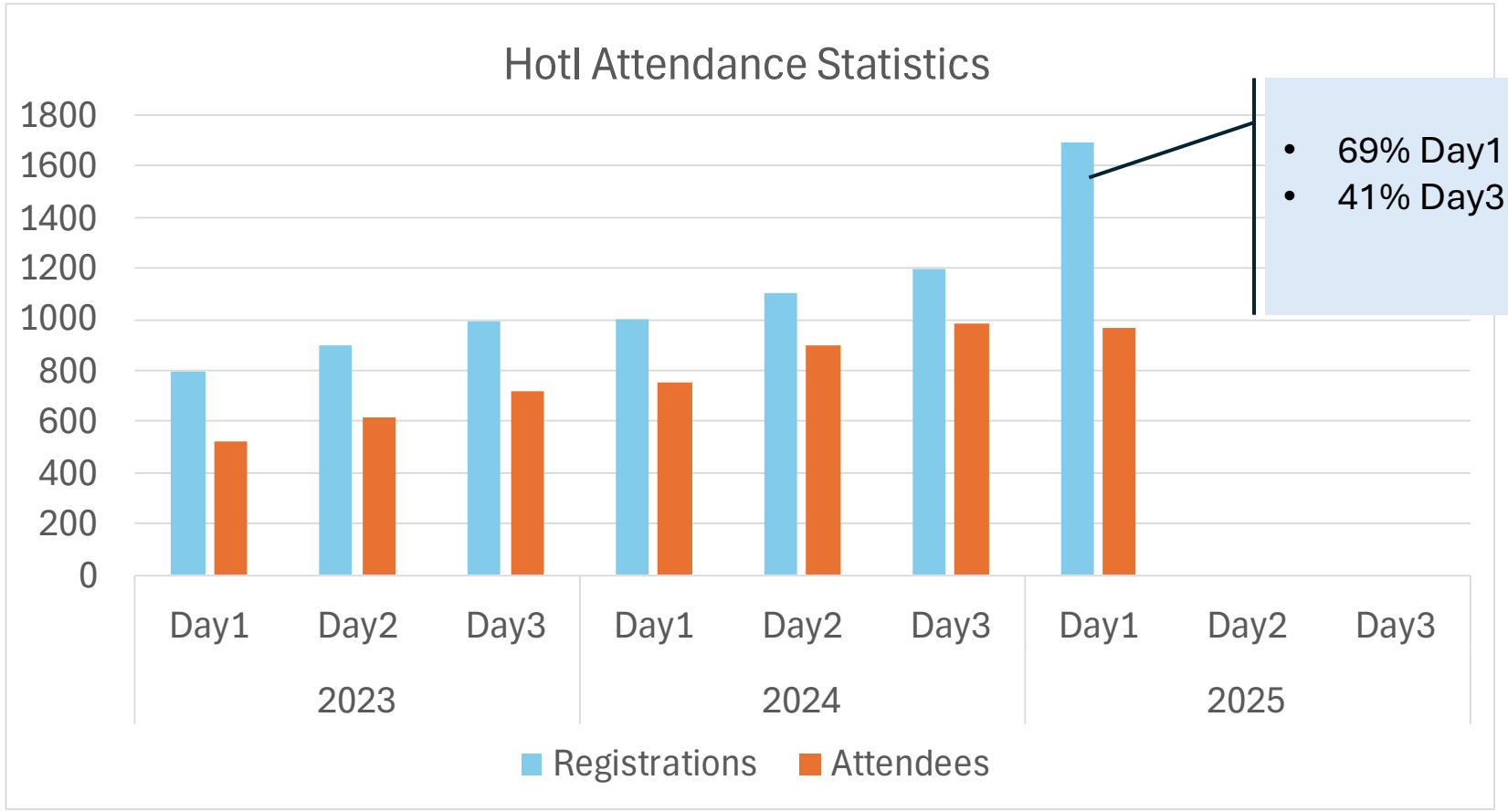
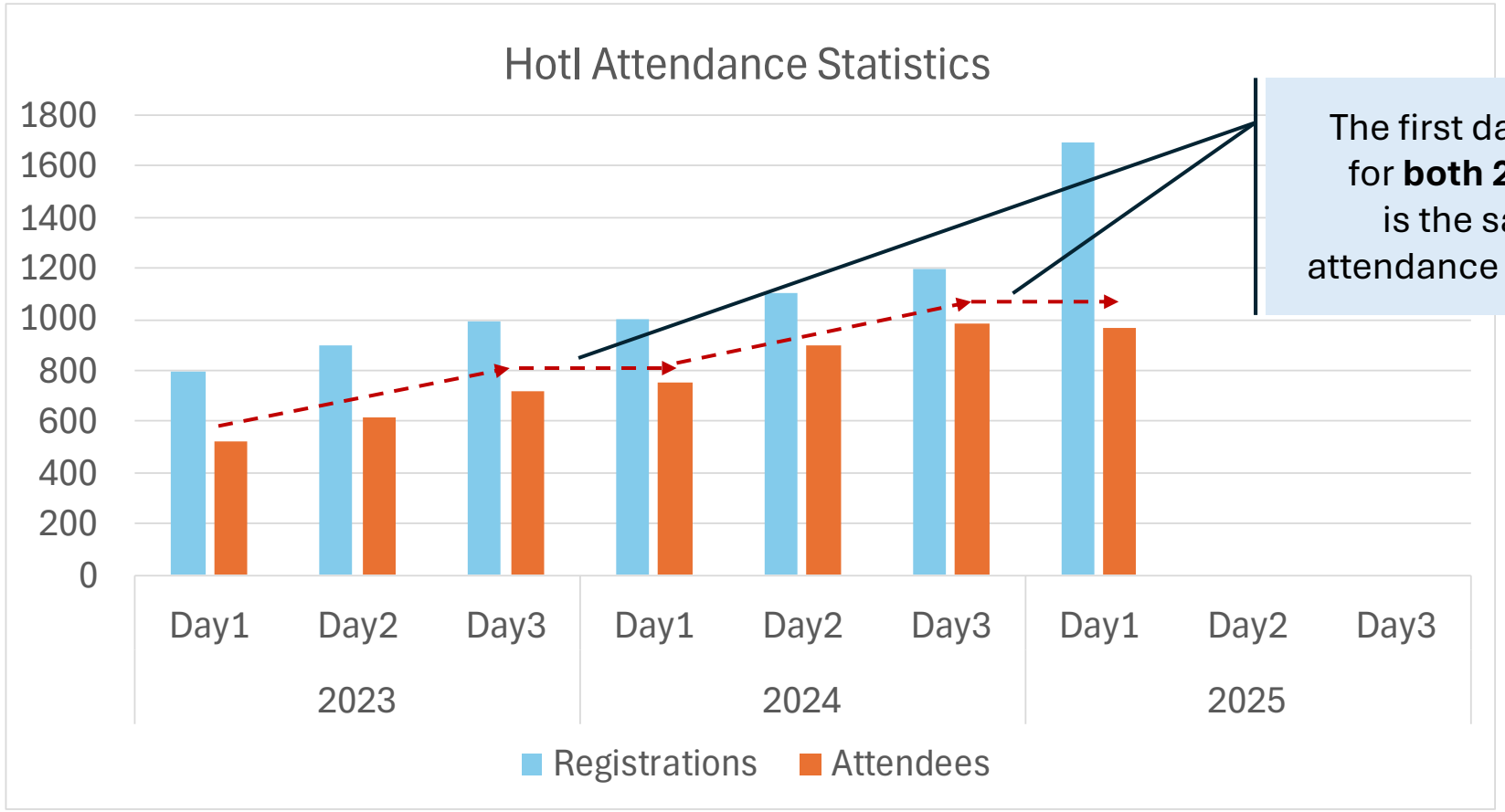


- 69% Day1 (2024) improvement
- 41% Day3 (2024) improvement

Day 1 Attendance Stats



The first day's attendance for **both 2024 and 2025** is the same as total attendance on previous year

Thank you for your support!

CORNELIS NETWORKS

nubis COMMUNICATIONS

CISCO

AVICENA

ARISTA

UALink

Meta

celestial AI

HOT INTERCONNECTS

GIGAIO

IEEE COMPUTER SOCIETY

HPCwire

Lenovo

DELL Technologies

FREE Registration

Music by:

THE DAYOFFS

OUT OF CONTEST

Art Police

Mayfield Park

Best Paper
Cash Award - $1000

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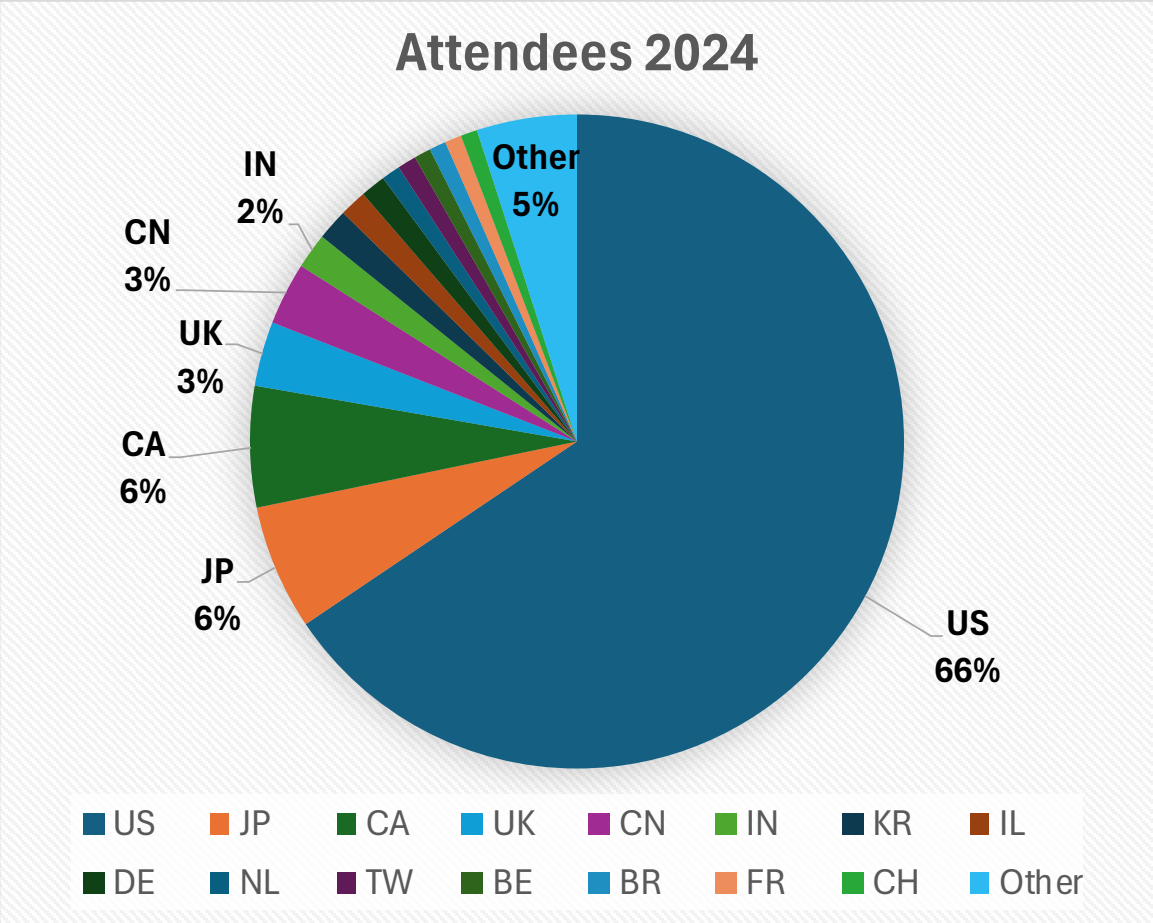
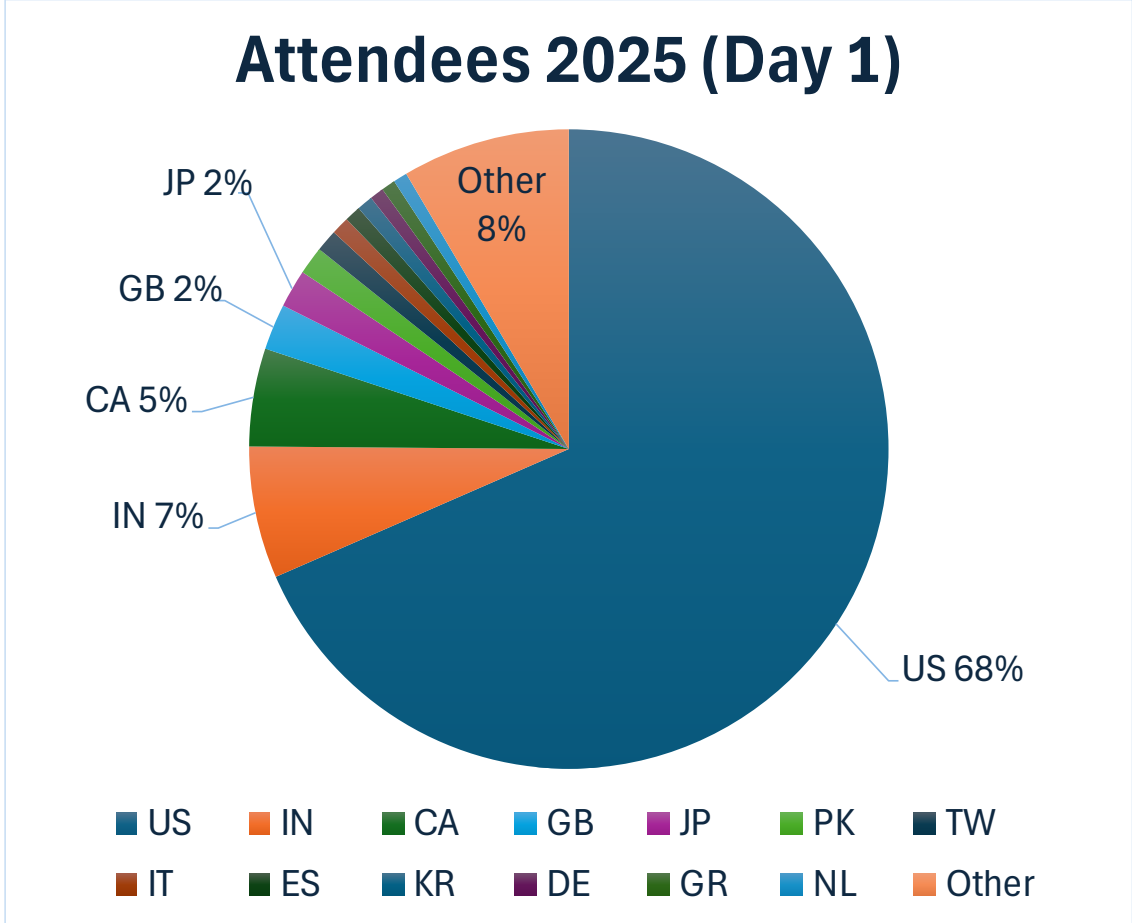
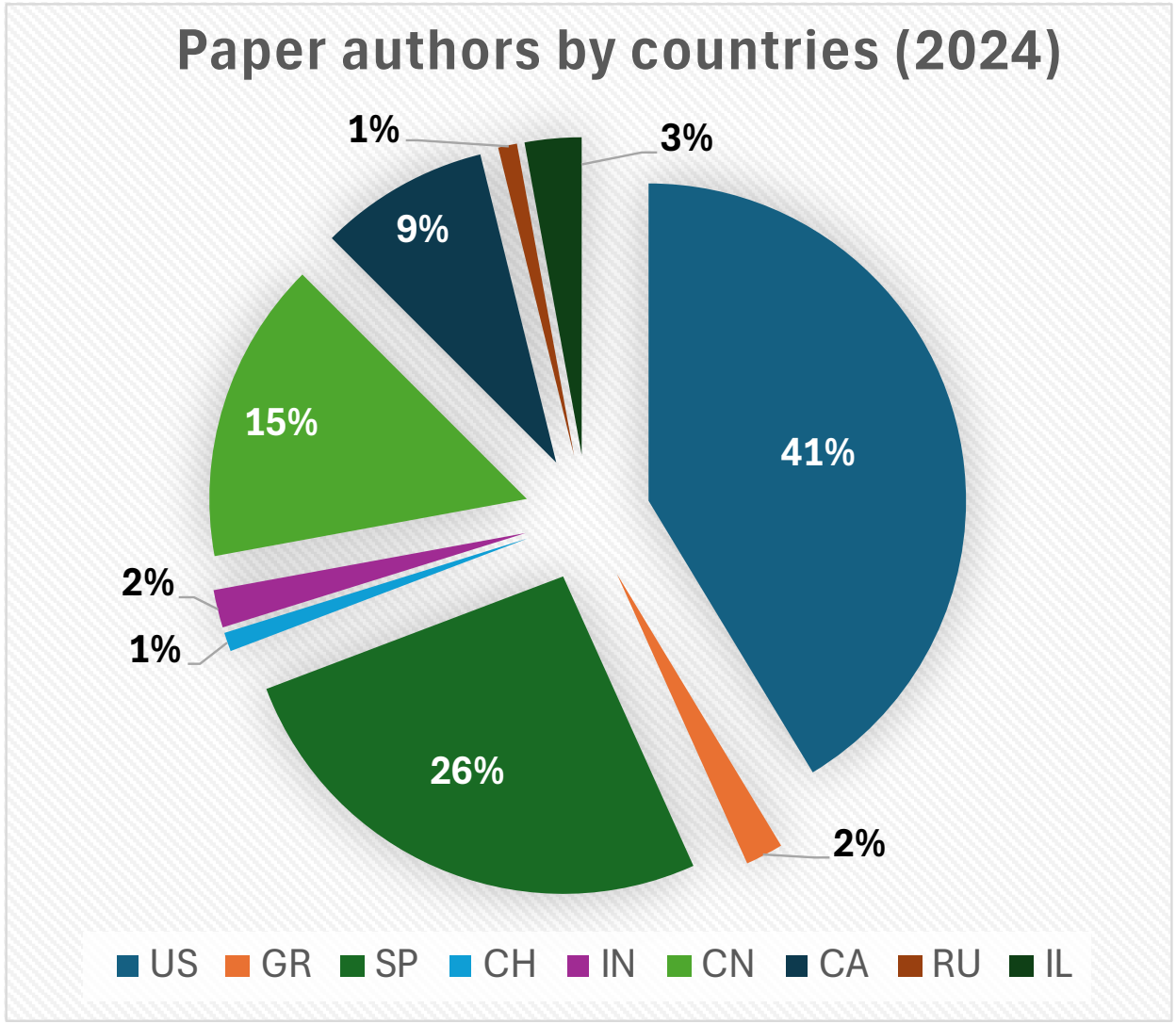


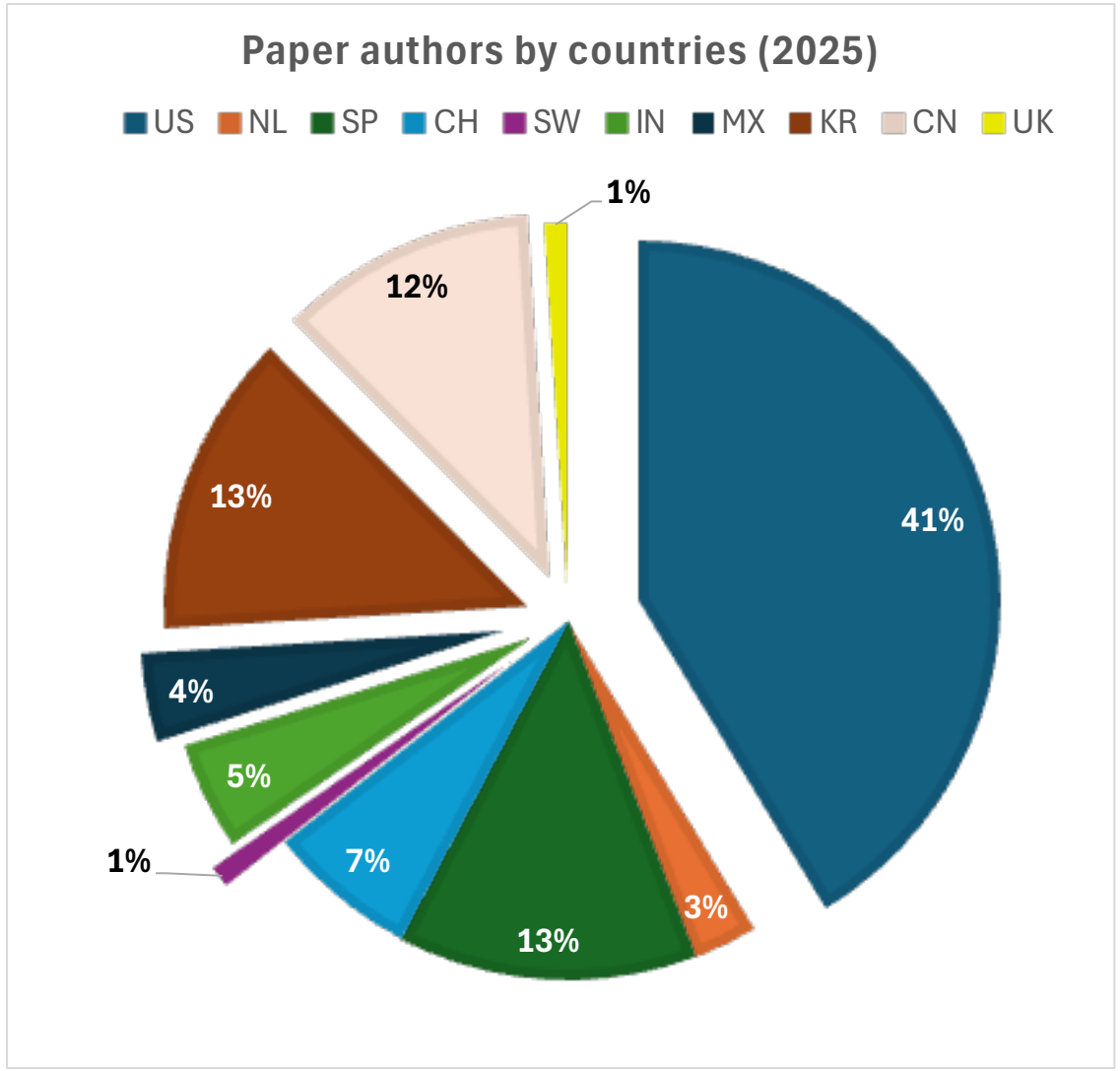
44 countries



48 countries

Submission statistics





Technical program (2025)

- HotI'25 Technical Program Committee (TPC)
  - 31 members
  - From
    - 19 organizations (37% Academia, 63% Industry)
    - France, Japan, South Korea, Spain, Switzerland, and US
- Peer review process
  - 4 reviews/paper
  - 9 Papers accepted
    - 8 full papers
    - 1 short hot-topic paper
  - Overall acceptance rate of 39%

HotI Technical Program Committee

Ferrol Aderholdt (NVIDIA)	Mohiuddin Mazumder (Intel)
Yuichiro Ajima (Fujitsu Limited)	Md Atiqul Mollah (Cornelis Networks)
Ron Brightwell (SNL)	Kaiming Ouyang (NVIDIA)
Ram Sharan Chaulagain (FSU)	Kishore Punniyamurthy (NVIDIA)
Swadesh Choudhary (Intel)	Raghunath Raja Chandrasekar (Amazon Web Services)
Jens Domke (RIKEN)	Adrien Roussel (CEA)
Hans Eberle (NVIDIA)	Galen Shipman (LANL)
Edgar Gabriel (AMD)	Craig Stunkel (NVIDIA)
Pedro Javier Garcia (UCLM, Spain)	Hugo Taboada (CEA)
Letizia Giuliano (Alphawave Semi)	Anant Thakar (Lightmatter)
Mitch Gusat (IBM Zurich)	Keith Underwood (HPE)
Jahanzeb Maqbool Hashmi (NVIDIA)	Vishwanath Venkatesan (NVIDIA)
Hyun-Wook Jin (Konkuk University)	Anna Verner (NVIDIA)
Jithin Jose (Microsoft)	Gwendolyn Voskuilen (SNL)
Shelby Lockhart (AMD)	Xin Yuan (FSU)
Xiaoyi Lu, (UC, Merced)	

HotI Organizing Committee (OC)

General Chair	Artem Polyakov	*NVIDIA*
Vice Chair	Sayan Ghosh	*Pacific Northwest National Laboratory*
PC Chairs	Rohit Zambre	*NVIDIA*
	David Ozog	*Cornelis Networks*
Keynote/Panel Chairs	Dan Pitt	*Palo Alto Innovation Advisors*
	Alan Benjamin	*GigaIO*
	Pavel Shamis	*NVIDIA*
	Taylor Groves	*Lightmatter*
Tutorial Chairs	Amanda Bienz	*UNM*
	Matthew Dosanjh	*Sandia National Laboratories*
Online Conference Chairs	Matthew Fricke	*UNM*
	Nicholas Sarkauskas	*NVIDIA*
	Pepper Marts	*HPE*
Web Chairs	Timothy Stamler	*NVIDIA*
	Yuke Li	*UC Merced*

Publicity Chairs	Subhadeep Bhattacharya	*NVIDIA*
	Don Draper	*ProPrincipia International Associates*
Finance Chairs	Scott Levy	*Sandia National Laboratories*
	Jim Dinan	*NVIDIA*
Publication Chairs	Nicola Andriolli	*University of Pisa*
	Shannon Kinkead	*Sandia National Laboratories*
Journal Chairs	Joseph Schuchart	*Stony Brook University*
	Whit Schonbein	*Sandia National Laboratories*
Sponsor Chairs	Raj Channa	*RBC Capital Markets*
	Emilio Paolini	*Scuola Superiore Sant'Anna*
Award Chairs	Ryan Grant	*Queen's University*
	Yiltan Temucin	*AMD*

HotI Steering Committee

Jim Dinan (Chair)	NVIDIA
Allen Baum	Esperanto Technologies
Raj Channa	RBC Capital Markets
Don Draper	ProPrincipia International Associates
Madeleine Glick	Columbia University
Manjunath Gorentla Venkata	NVIDIA
Ryan Grant	Queen's University
Mitch Gusat	IBM Research
John Lockwood	Algo-Logic Systems
Fabrizio Petrini	Intel Labs
Dan Pitt	Palo Alto Innovation Advisors
Xinyu Que	IBM Research
Pavel Shamis	NVIDIA

Yesterday's poll

How did you hear about Hot-I?

Poll ended | 1 question | 125 total responses

1. How did you learn about HotI this year?
(Multiple choice)

125/125 (100%) answered

I follow the event on yearly basis	(58/125) 46%
LinkedIn	(26/125) 21%
From HPC announcement email list	(9/125) 7%
X/Twitter	(3/125) 2%
Hot Interconnects mailing list	(21/125) 17%
It was recommended to me by someone	(30/125) 24%
Other	(9/125) 7%

HotI Social Media

https://www.linkedin.com/company/hot-interconnects

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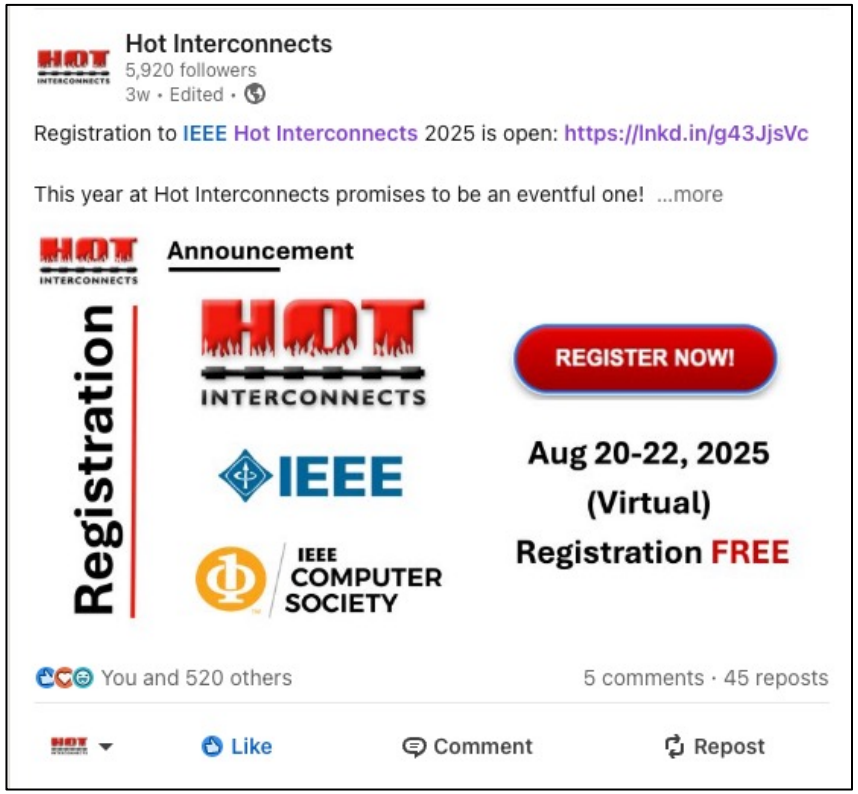

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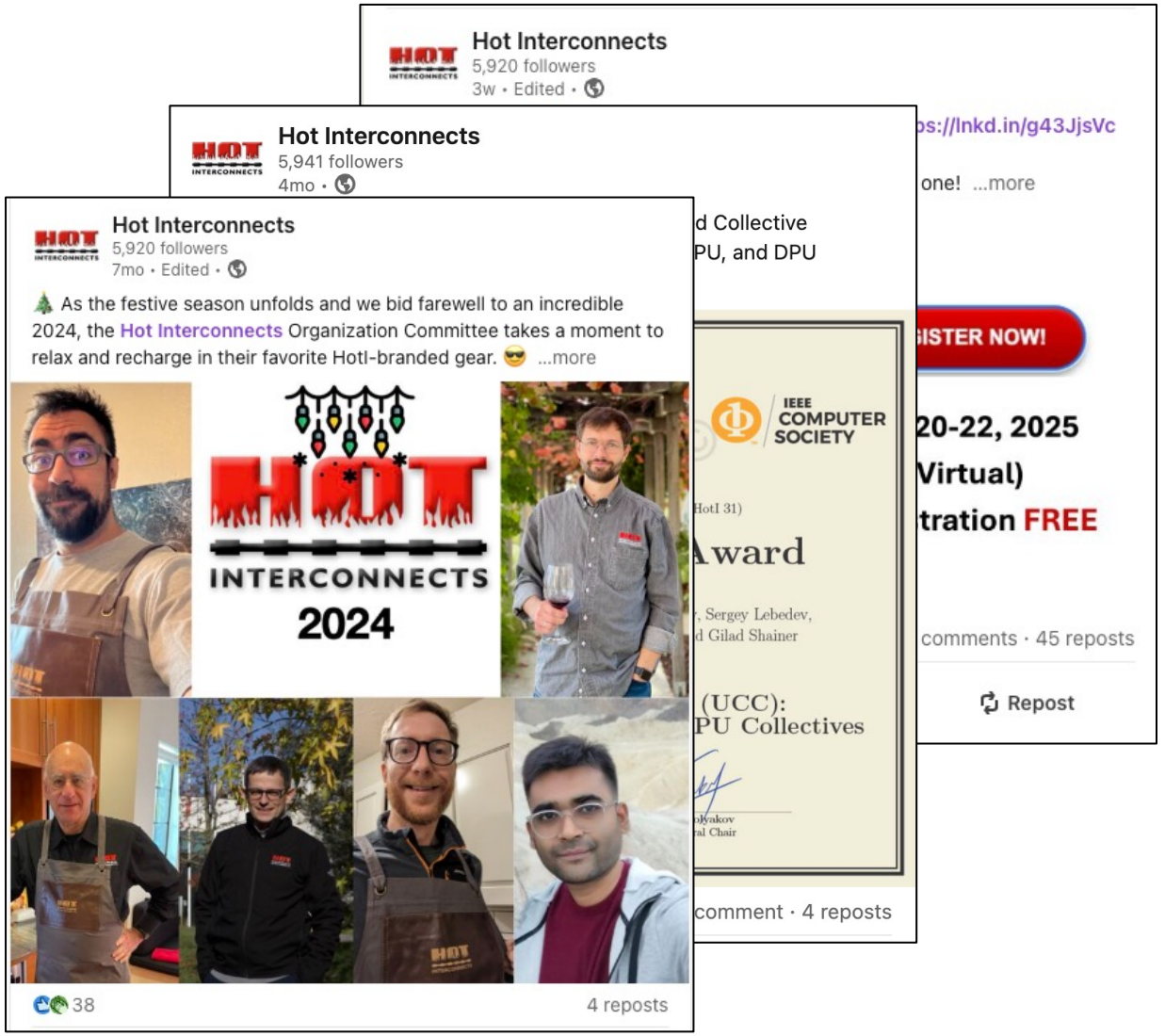

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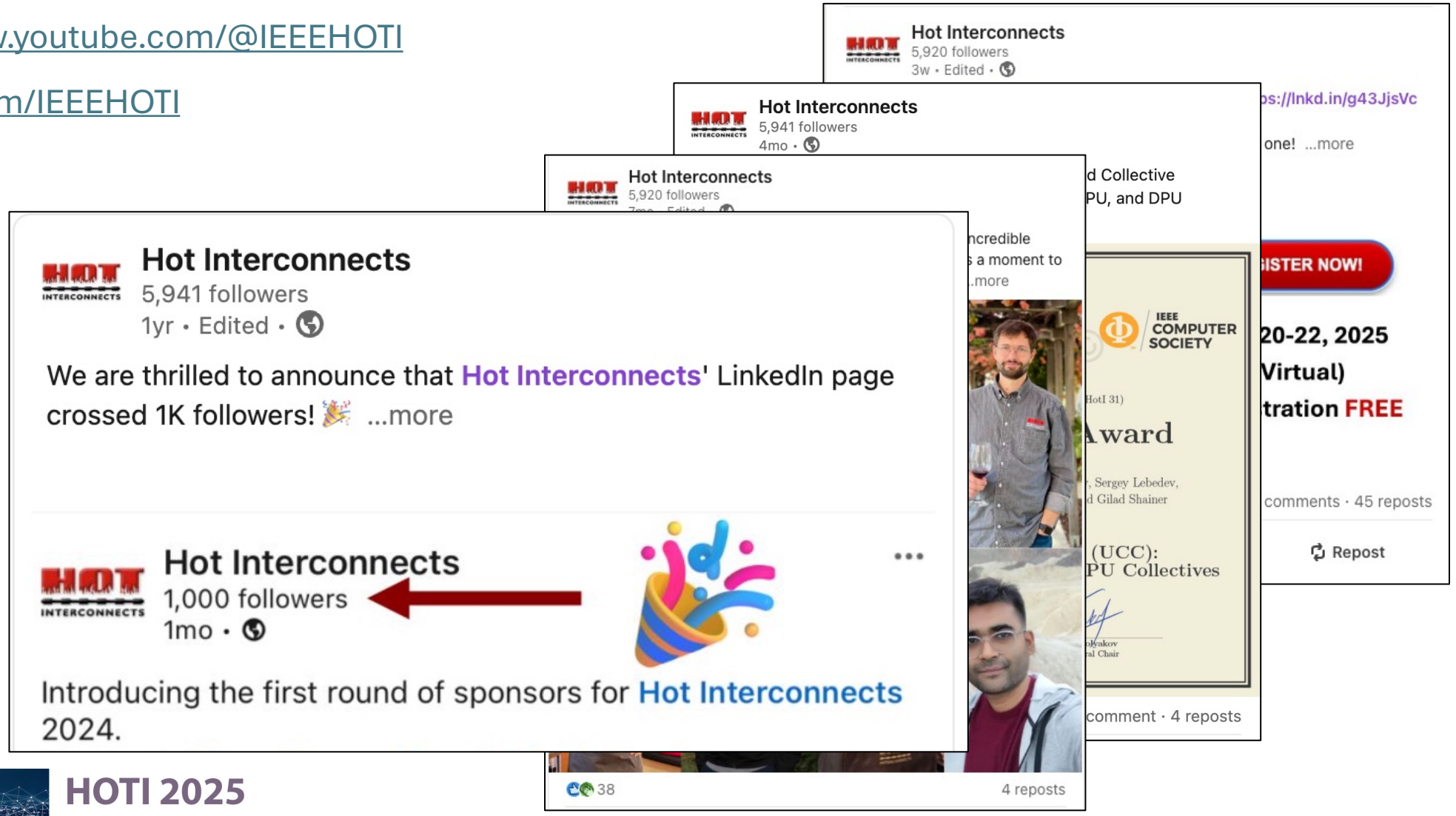

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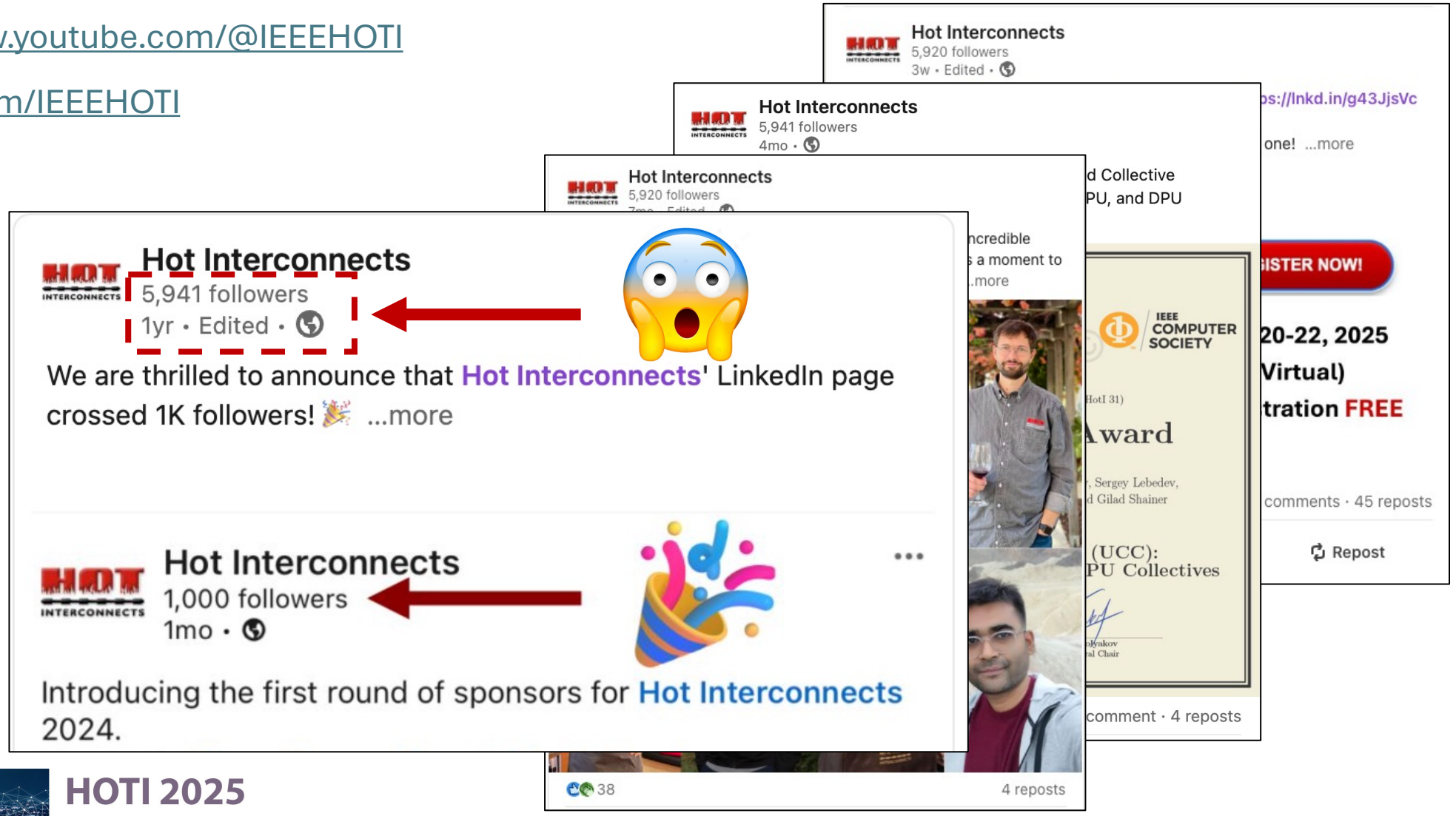

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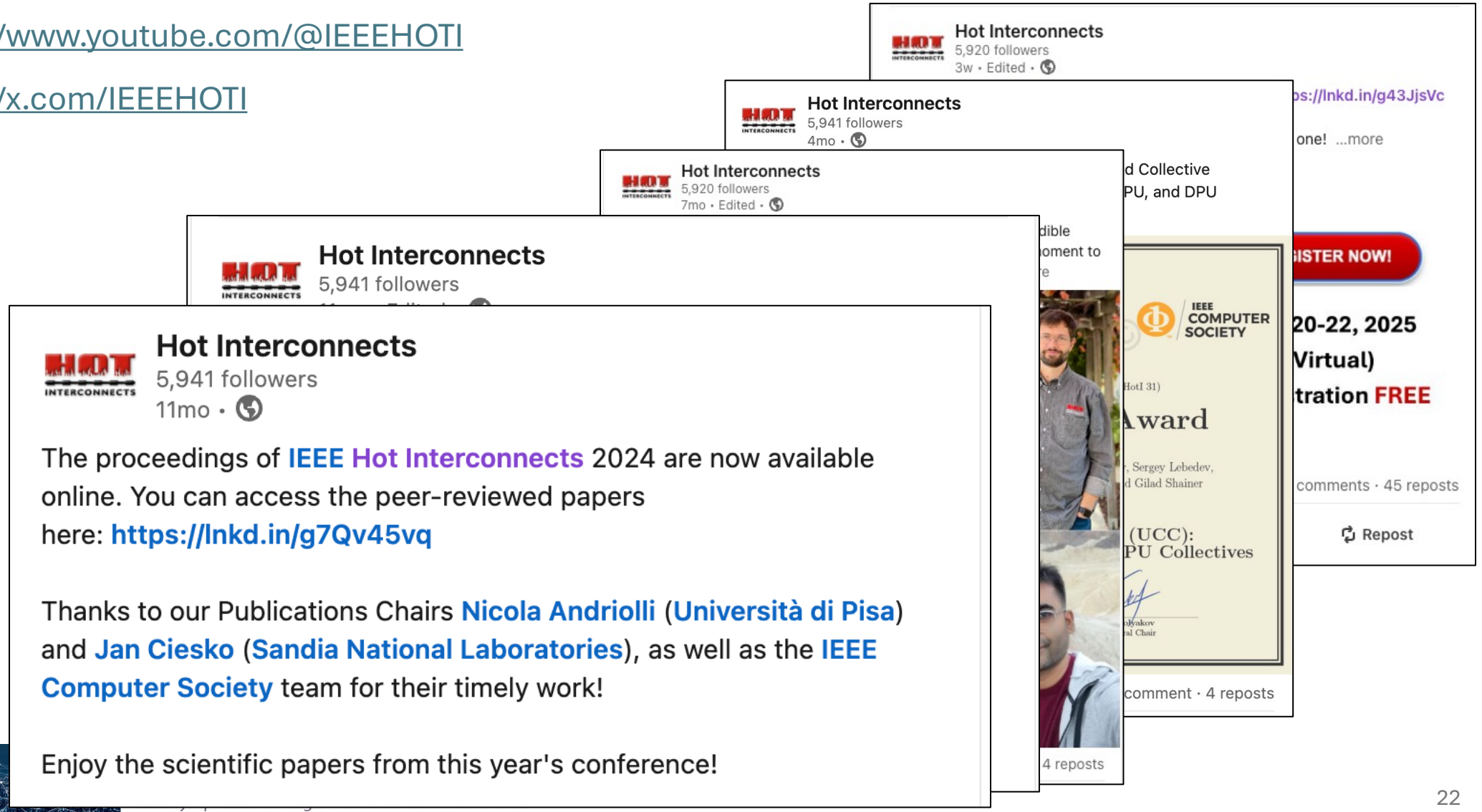

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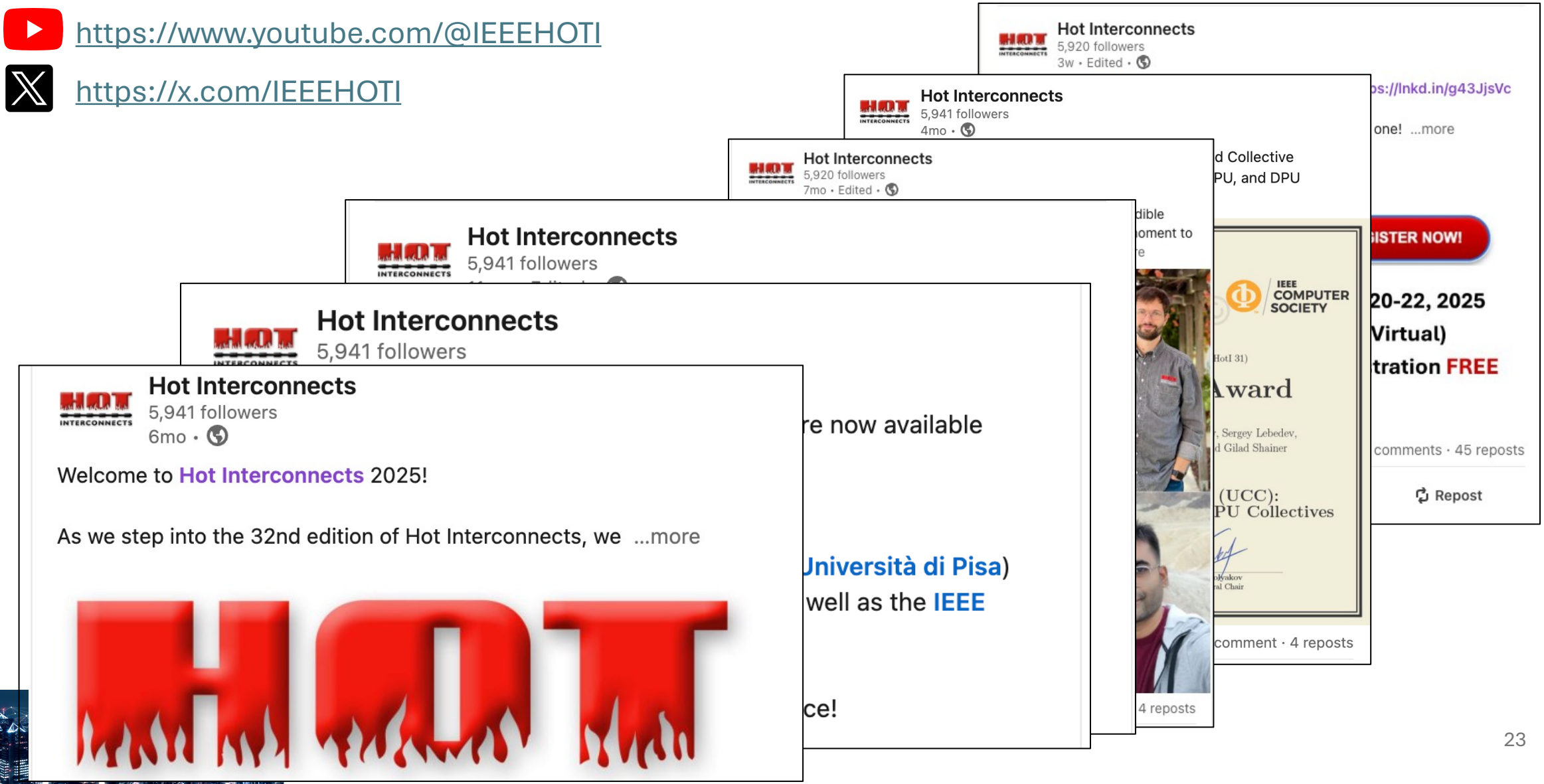

HotI Social Media

Day2 … let’s start!

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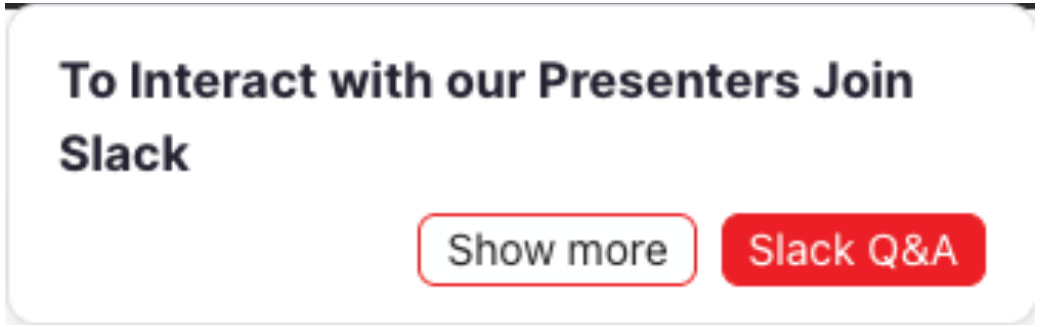
Attendee Information

Questions and Answers

are conducted via SLACK!

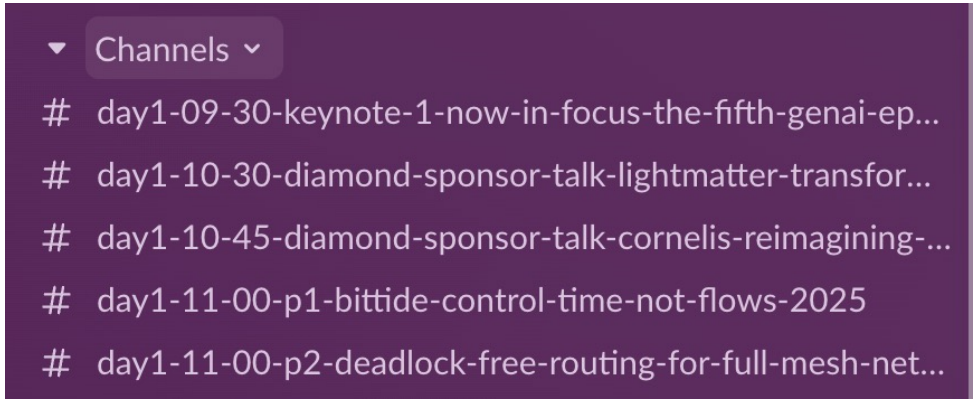
Step1. Find the link to join in Zoom Lobby (top-right corner)



http://bit.ly/4lBoSLc

Early access to proceedings
https://hoti.org/program.html

Step2. Individual channel for each talk



HotI Day2

- **Keynote 2**
  "*Evolving inter-connect fabric and SDN in the cloud to meet the needs of AI*"
  Deepak Bansal (Microsoft)
- **Sponsor talks session**: Avicena, Arista, GigaIO
- **Technical Paper Session C**:
  Interconnect Software – Runtimes & Workloads
- *Lunch*
- **Invited Talk Session:** Next Gen Interconnects
  - Ultra Ethernet for next-generation AI and HPC workloads, Torsten Hoefler (ETH Zurich)
  - Building Custom AI Infrastructure with NVLink Fusion, Krishnan Geeyarpuram (NVIDIA)
- **Sponsor talks session**: UALink, Celestial AI, Meta
- **Technical Paper Session D**: Scale-up Interconnects
- **HotI Awards & Closing Remarks**